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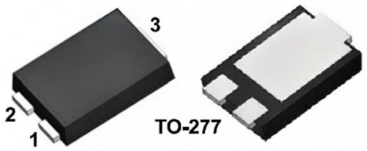
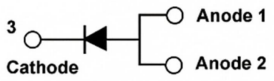
FSV15100V
15 A, 100 V Ultra-Low VF Schottky Rectifier

Features

- Ultra-Low Forward Voltage Drop
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- Trench Schottky Technology
- RoHS Compliant
- Green Molding Compound as per IEC61249 Standard
- Lead Free in Compliance with EU RoHS 2011/65/EU Directive
- Qualified per AEC-Q101 Rev. C Standard





Ordering Information

Part Number	Top Mark	Package	Packing Method
FSV15100V	FSV15100V	TO-277 3L	Tape and Reel

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at T_A = 25°C unless otherwise noted.

Symbol	Parameter	Value	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	100	V
V_{RWM}	Working Peak Reverse Voltage	100	V
V_{RMS}	RMS Reverse Voltage	70	V
V_R	DC Blocking Voltage	100	V
$I_{F(AV)}$	Average Rectified Peak Forward Surge Current	15	A
I_{FSM}	Non-Repetitive Peak Forward Surge Current	250	A
T_J	Operating Junction Temperature Range	-55 to +150	°C
T_{STG}	Storage Temperature Range	-55 to +150	°C

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Thermal Characteristics(1)

Values are at T_A = 25°C unless otherwise noted.

Symbol	Parameter	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	100	40	°C/W
Ψ_{JL}	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	°C/W
	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	

Note:

1. The thermal resistances ($R_{\theta JA}$ & Ψ_{JL}) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



Figure 1. Minimum Land Pattern of 2 oz Copper

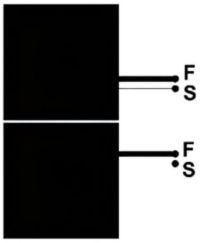

Figure 2. Maximum Land Pattern of 2 oz Copper

Electrical Characteristics

Values are at T_A = 25°C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_R	Breakdown Voltage	I_R = 0.5 mA	100			V
V_F	Forward Voltage Drop	I_F = 15 A		0.613	0.660	V
I_R	Reverse Current	V_R = 100 V		28	80	μA

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Typical Performance Characteristics

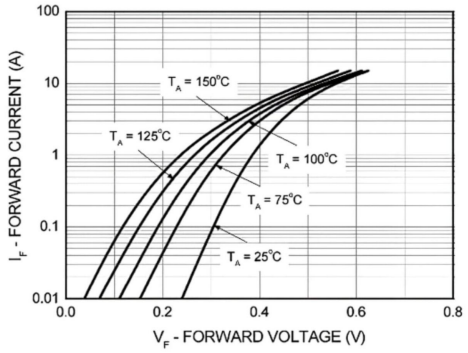

Figure 3. Typical Forward Characteristics

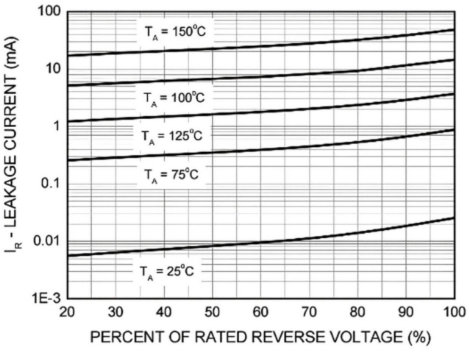

Figure 4. Typical Reverse Characteristics

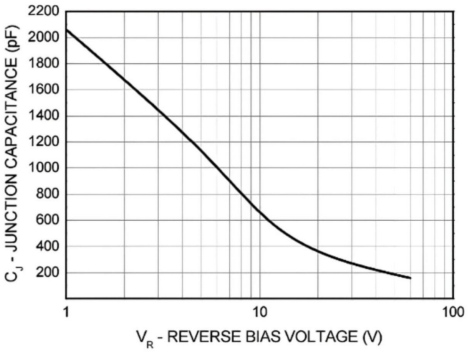

Figure 5. Typical Junction Capacitance

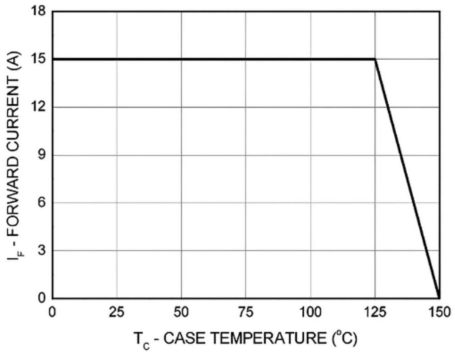

Figure 6. Forward Current Derating Curve

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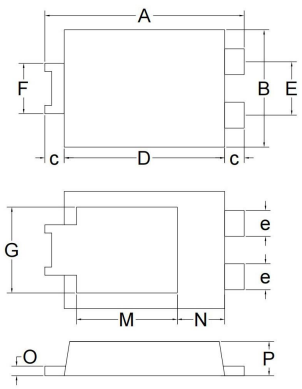
Ordering Information

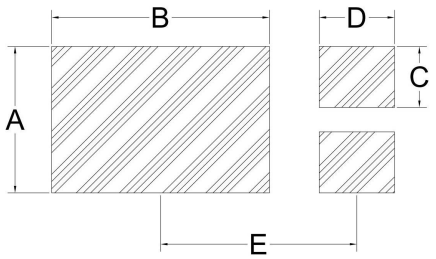
PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
TO-277	R3	0.090	5000	10000	100000	13''

Package Outline Dimensions (TO-277)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	6.300	6.700	0.248	0.264
B	3.950	4.300	0.156	0.169
c	0.410	0.710	0.016	0.028
D	5.280	5.880	0.208	0.231
E	1.760	1.960	0.069	0.077
e	0.850	0.960	0.033	0.038
F	1.750	1.850	0.069	0.073
G	2.850	3.150	0.112	0.124
M	3.390	3.690	0.133	0.145
N	1.440	1.740	0.057	0.069
O	0.250	0.350	0.010	0.014
P	0.950	1.250	0.037	0.049

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.400	3.800	0.134	0.150
B	4.500	4.900	0.177	0.193
C	1.200	1.600	0.047	0.063
D	0.600	1.00	0.024	0.039
E	3.670	4.070	0.144	0.160